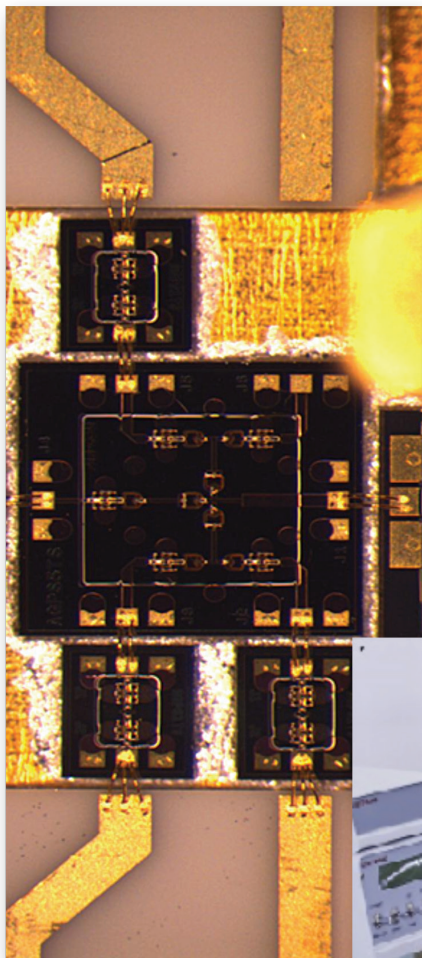


Thin Film Fabrication Services



Your Solution for Fabrication and Assembly Needs

Anritsu Microelectronics Fabrication Center, conveniently located south of Silicon Valley in Morgan Hill, CA, includes an 8,000 sq. ft. class 100/10,000 clean room, a 25,000 sq. ft. RF/microwave assembly manufacturing facility, and a state-of-the-art machining center. We are proud to be your partner for thin film device fabrication, microelectronic assembly, packaging, and machining.

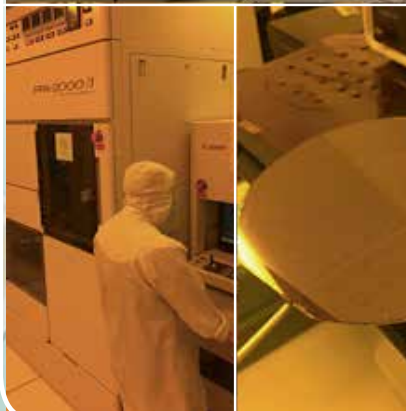
QUALITY

Custom Thin Film Devices
GaAs/InP Optoelectronics Wafer Foundry
MEMs
Rapid Prototyping

RELIABILITY

High-Volume, High-Quality
Production Process Engineering
Support Microelectronic Assembly
Testing and Machining

FLEXIBILITY



Thin Film Fab

Photolithography

5x stepper, contact lithography, double-sided aligning available

Etching

Plasma, RIE, wet etching of metal, silicon, nitride, and oxide

Dielectric Deposition

Plasma-enhanced CVD

Metal Deposition

Sputtering, E-beam evaporation

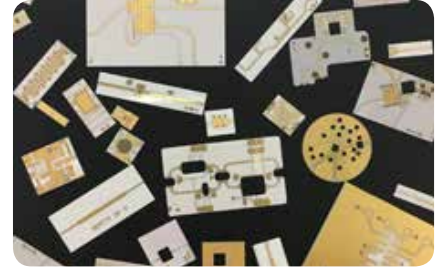
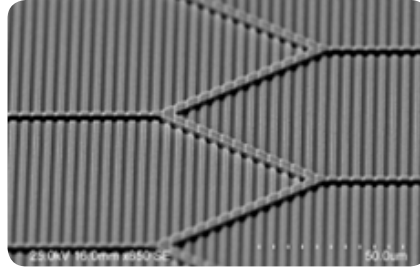
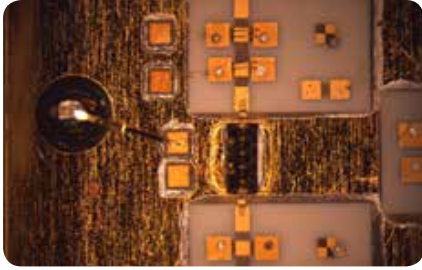
Other Process Capabilities

Selective gold and AuSn electroplating
Polyimide, BCB, and Si₃N₄ capacitors
Integrated resistors
Filled and plated through vias
Wrap-arounds
Precision laser resistor trimming
Full support custom product development

Material

Alumina, aluminum nitride, fused silica, sapphire, glass, silicon, GaAs and InP wafers, CVD diamond, etc.

Anritsu Company is a global leader in RF/microwave test and measurement equipment for laboratories and field applications.



• CONVENIENCE

• QUICK DELIVERY

Markets Served

- Telecommunications
- Civil Aviation and Aerospace
- Automotive
- Defense
- Biotechnology and Medical
- Solar



Microelectronic Manufacturing

Assembly Equipment and capabilities

Auto wedge bonder, SEM, acoustic microscope, eutectic die attach, epoxy die attach, flip chip attach, gap welding, wedge bonding, tack bonding, ball bonding, sheet epoxy attach, non-conductive epoxy attach, hermetically sealed connector assembly, soldering (*AuSn, Indium, SnPb, Gold Germanium, RoHs compliant solders available*)

Testing

DC-220 GHz range, S-parameters, Noise Figure, noise floor, dynamic range, IIP3/OIP3, harmonic levels, phase noise

Reliability Testing

IC thermal imaging, material analysis, HALT and HASS testing, environmental testing, burn-in, power cycling, EMI/EMC testing, drop testing, die attach void testing, temperature cycle with or without testing, shear and pull testing

Machining

CNC and manual mills and lathes

Anritsu RF/Microwave Manufacturing Services

Anritsu Company is the United States subsidiary of Anritsu Corporation, a global provider of innovative communications test and measurement solutions for 120 years. Anritsu's "2020 VISION" philosophy engages customers as true partners to help develop wireless, optical, RF/microwave, and digital instruments, as well as operation support systems for R&D, manufacturing, installation, and maintenance applications.

Anritsu also provides precision RF/microwave components, optical devices, and high-speed electrical devices for communication products and systems. The company develops advanced solutions for 5G, M2M, IoT, as well as other emerging and legacy wireline and wireless applications. With offices throughout the world with approximately 4,000 employees, Anritsu's products are sold in over 90 countries.

To learn more about our services, please email us at **thinfilm@Anritsu.com**



Anritsu utilizes recycled paper and environmentally conscious inks and toner.



® Anritsu All trademarks are registered trademarks of their respective owners. Data subject to change without notice. For the most recent specifications visit: www.anritsu.com

11410-00911, Rev. C Printed in United States 2020-07
©2020 Anritsu Company. All Rights Reserved.